

METHOD OF MAKING PRINTED CIRCUIT BOARD WITH ELECTROPLATED CONDUCTIVE THRU HOLES AND BOARD RESULTING THEREFROM

ABSTRACT

A method of electrolytically plating a layer of metal on the internal surface of an opening within a substrate so as to deposit a substantially uniform layer of metal on the internal surface of the opening. The method comprises substantially immersing a substrate having an opening therein within an electroplating bath containing ions of a metal to be deposited onto the internal surface of the opening and passing an electric current through the bath wherein the current includes modulated forward and reverse pulses, selected ones of the forward and/or reverse pulses followed by a pause in the electric current. A printed circuit board produced using this method is also provided.